

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC079N03LSC G	**Issued**	1. August 2018
MA#	MA001779986		
Package	PG-TDSON-8-40	**Weight***	111.53 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.709	0.64	0.64	6356	6356
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		131	
	non noble metal	iron	7439-89-6	0.049	0.04		437	
	non noble metal	copper	7440-50-8	48.649	43.63	43.68	436214	436782
wire	non noble metal	copper	7440-50-8	0.059	0.05	0.05	528	528
encapsulation	organic material	carbon black	1333-86-4	0.085	0.08		760	
	plastics	epoxy resin	-	6.698	6.01		60057	
	inorganic material	silicondioxide	60676-86-0	35.610	31.93	38.02	319292	380109
leadfinish	non noble metal	tin	7440-31-5	1.520	1.36	1.36	13629	13629
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1421	1421
solder	non noble metal	tin	7440-31-5	0.021	0.02		187	
	noble metal	silver	7440-22-4	0.026	0.02		234	
	non noble metal	lead	7439-92-1	0.996	0.89	0.93	8932	9353
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		46	
	non noble metal	iron	7439-89-6	0.017	0.02		152	
	non noble metal	copper	7440-50-8	16.910	15.16	15.18	151624	151822
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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